

1/18

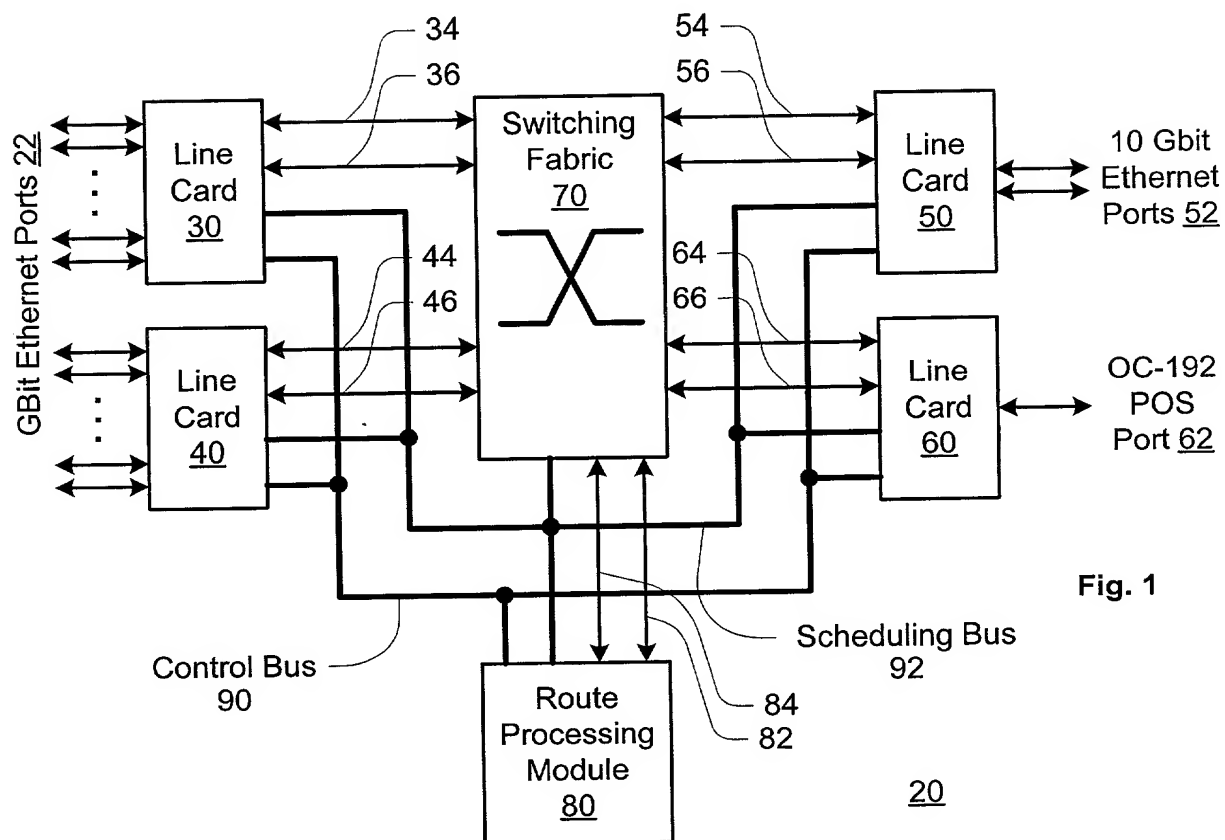


Fig. 1

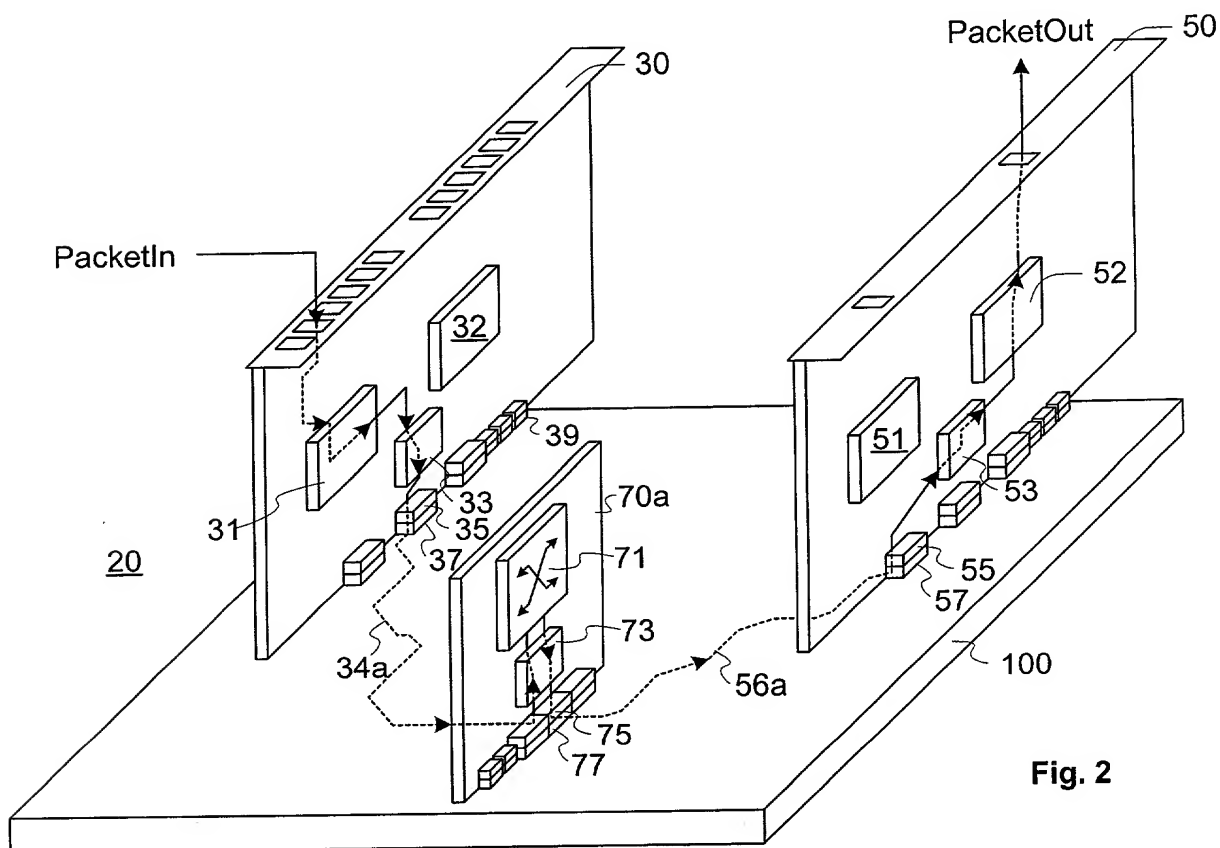


Fig. 2

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100

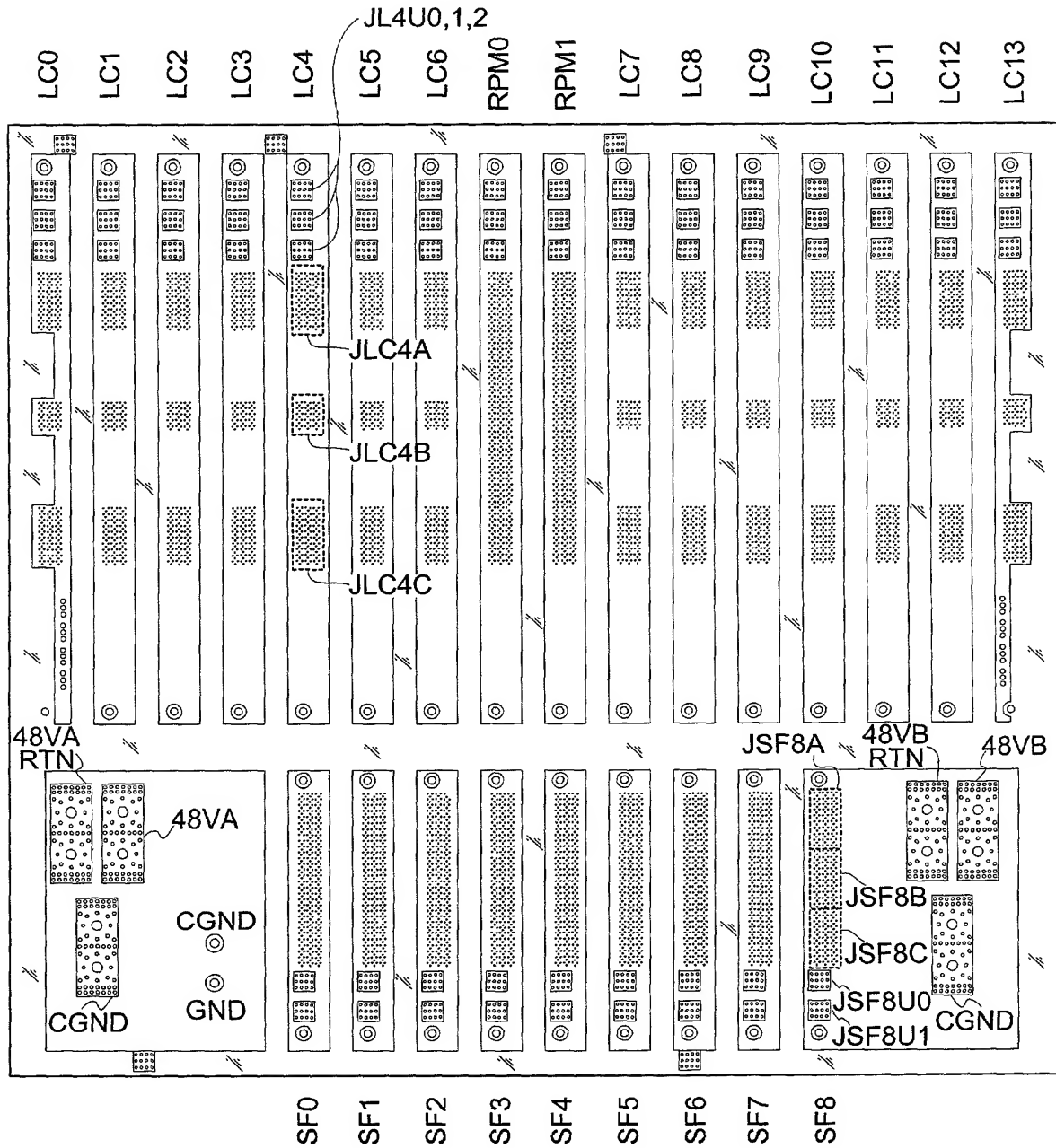


Fig. 3

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100

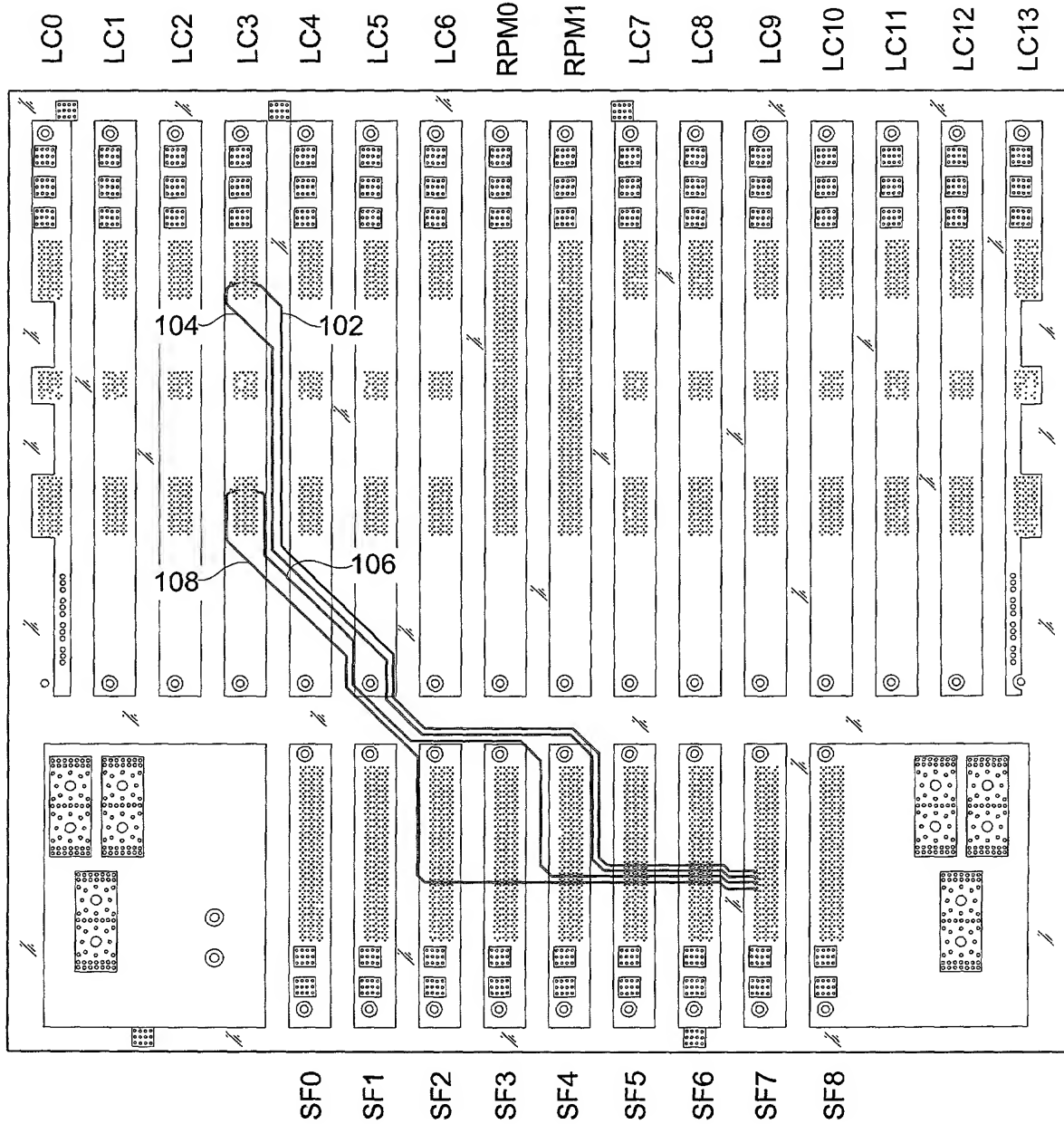


Fig. 4

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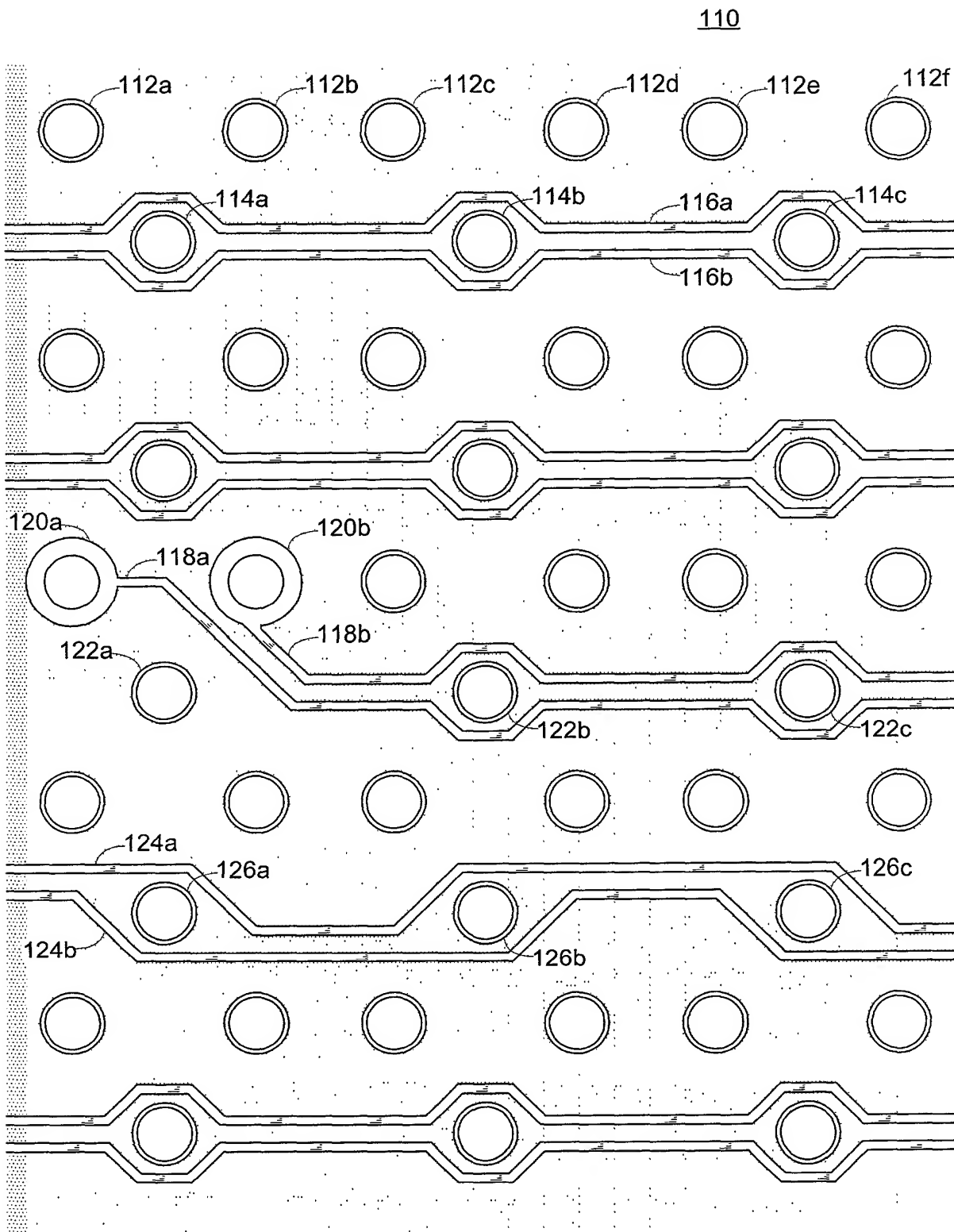


Fig. 5

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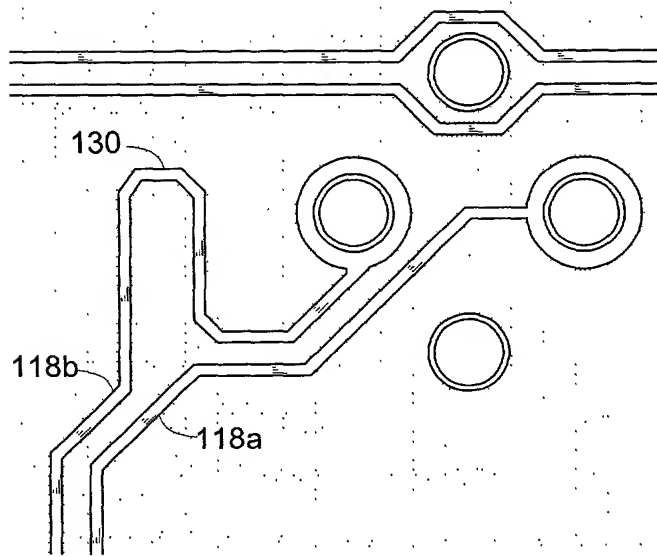


Fig. 6

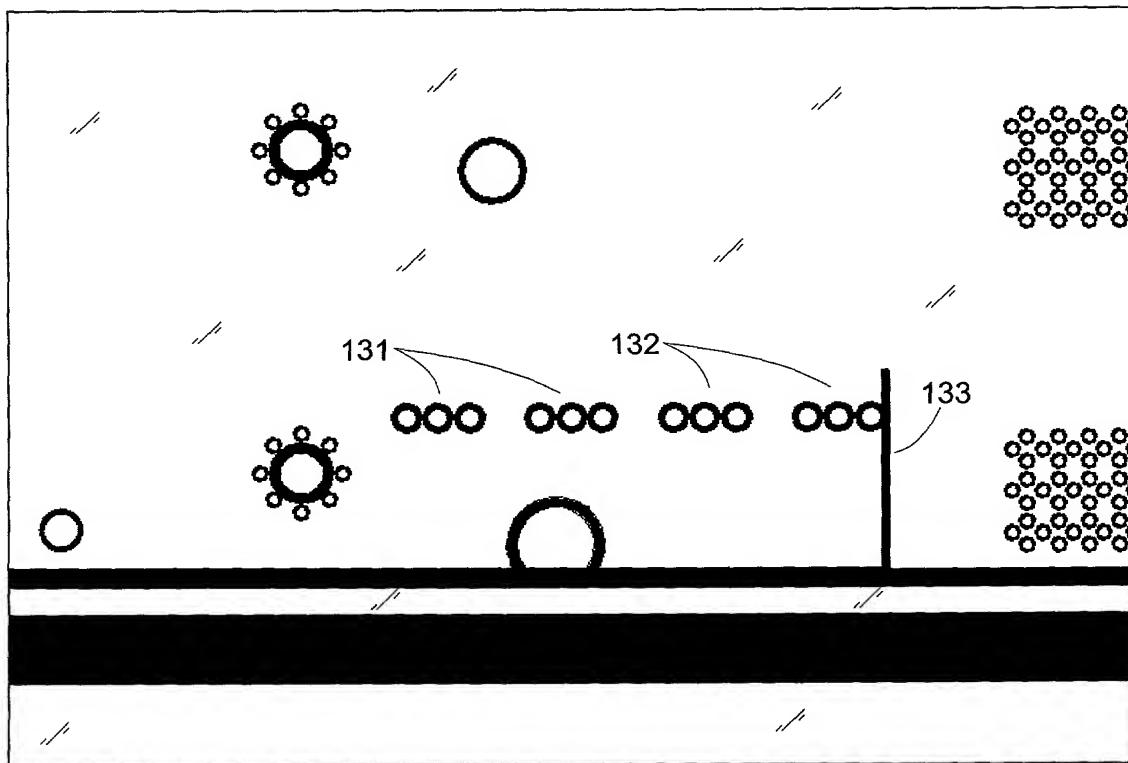
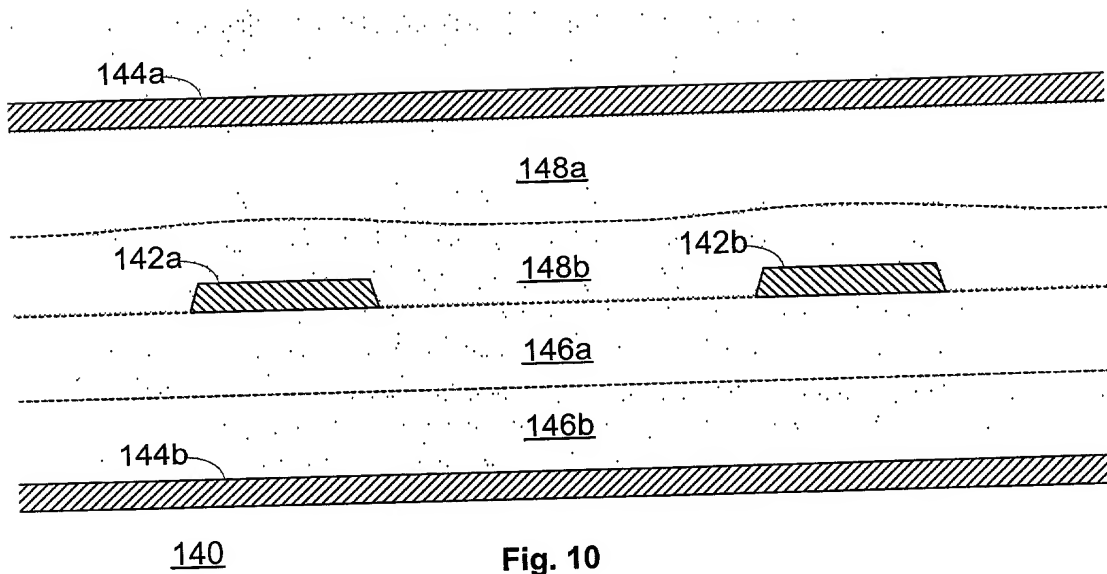
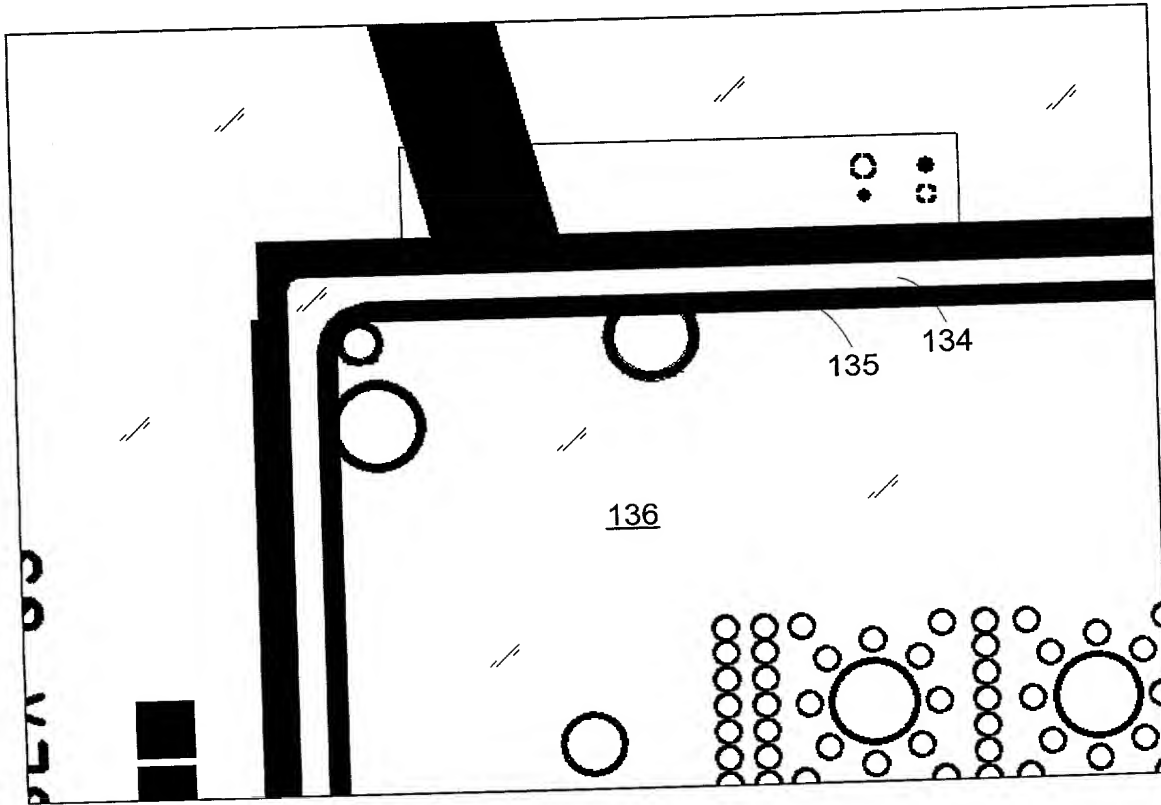


Fig. 7A



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Conductive Layers			8/18	Insulating Layers	
Layer No.	Thickness	Type		Type	Thickness
L01 --{	2.0	Foil/Plating		Mask	0.7
	1.2	Pads		B-stage	5.4
L02	1.4	GND		Core	7.5
L03	1.4	HS1		B-stage	6.9
L04	1.4	GND		Core	7.5
L05	1.4	HS2		B-stage	6.9
L06	1.4	GND		Core	7.5
L07	1.4	HS3		B-stage	6.9
L08	1.4	GND		Core	7.5
L09	1.4	HS4		B-stage	6.9
L10	1.4	GND		Core	7.5
L11	1.4	HS5		B-stage	6.9
L12	1.4	GND		LS Core	5.0
L13	1.4	Signal x1		LS B-stage	4.0
L14	1.4	Signal y1		LS Core	5.0
L15	1.4	GND		LS B-stage	6.0
L16	5.6	A 48V rtn		LS Core	6.0
L17	5.6	A 48V dc		LS B-stage	8.8
L18	5.6	B 48V dc		LS Core	6.0
L19	5.6	B 48V rtn		LS B-stage	6.0
L20	1.4	GND		LS Core	5.0
L21	1.4	Signal y2		LS B-stage	4.0
L22	1.4	Signal x2		LS Core	5.0
L23	1.4	GND		B-stage	6.9
L24	1.4	HS6		Core	7.5
L25	1.4	GND		B-stage	6.9
L26	1.4	HS7		Core	7.5
L27	1.4	GND		B-stage	6.9
L28	1.4	HS8		Core	7.5
L29	1.4	GND		B-stage	6.9
L30	1.4	HS9		Core	7.5
L31	1.4	GND		B-stage	6.9
L32	1.4	HS10		Core	7.5
L33	1.4	GND		B-stage	5.4
L34 --{	1.2	Pads		Mask	0.7
	2.0	Foil/Plating			

Fig. 8

Conductive Layers			9/18	Insulating Layers	
Layer No.	Thickness	Type		Type	Thickness
L01 --{	2.0	Foil/Plating		Mask	0.7
	1.2	Pads		B-stage	5.4
L02	1.4	GND		Core	7.5
L03	1.4	HS1		B-stage	6.5
L04	1.4	GND		Core	7.5
L05	1.4	HS2		B-stage	6.5
L06	1.4	GND		Core	7.5
L07	1.4	HS3		B-stage	6.5
L08	1.4	GND		Core	7.5
L09	1.4	HS4		B-stage	6.5
L10	1.4	GND		Core	7.5
L11	1.4	HS5		B-stage	6.5
L12	1.4	GND		Core	7.5
L13	1.4	Signal x1		B-stage	4.0
L14	1.4	Signal y1		Core	7.5
L15	1.4	GND		Lam 2 B-stg	9.0
				Lam 1 B-stg	8.5
L16	5.6	A 48V rtn		Core	6.0
L17	5.6	A 48V dc		Lam 1 B-stg	8.5
				Lam 2 B-stg	12.0
				Lam 1 B-stg	8.5
L18	5.6	B 48V dc		Core	6.0
L19	5.6	B 48V rtn		Lam 1 B-stg	8.5
				Lam 2 B-stg	9.0
L20	1.4	GND		Core	7.5
L21	1.4	Signal y2		B-stage	4.0
L22	1.4	Signal x2		Core	7.5
L23	1.4	GND		B-stage	6.9
L24	1.4	HS6		Core	7.5
L25	1.4	GND		B-stage	6.9
L26	1.4	HS7		Core	7.5
L27	1.4	GND		B-stage	6.9
L28	1.4	HS8		Core	7.5
L29	1.4	GND		B-stage	6.9
L30	1.4	HS9		Core	7.5
L31	1.4	GND		B-stage	6.9
L32	1.4	HS10		Core	7.5
L33	1.4	GND		B-stage	5.4
L34 --{	1.2	Pads		Mask	0.7
	2.0	Foil/Plating			

Fig. 9

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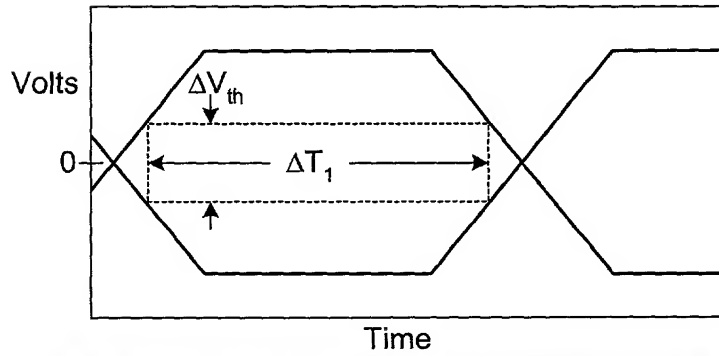


Fig. 11

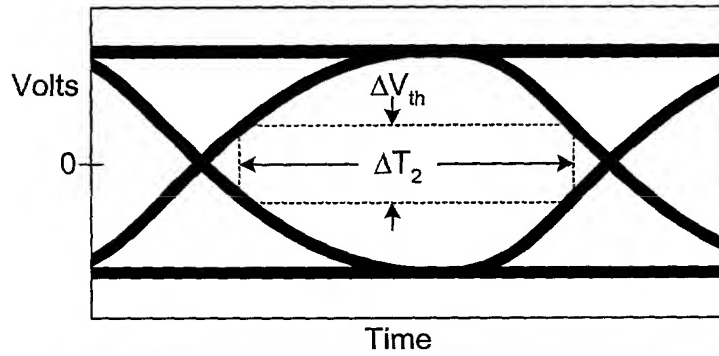


Fig. 12

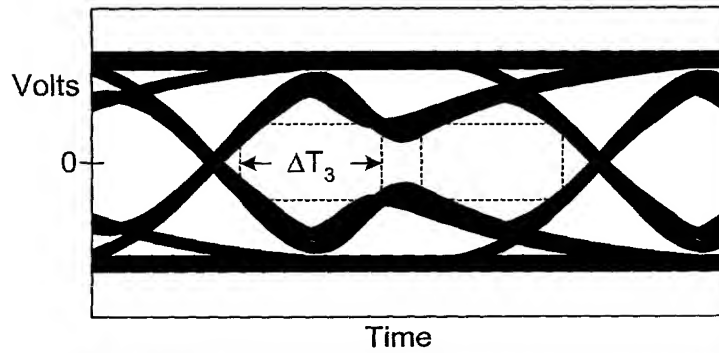


Fig. 13

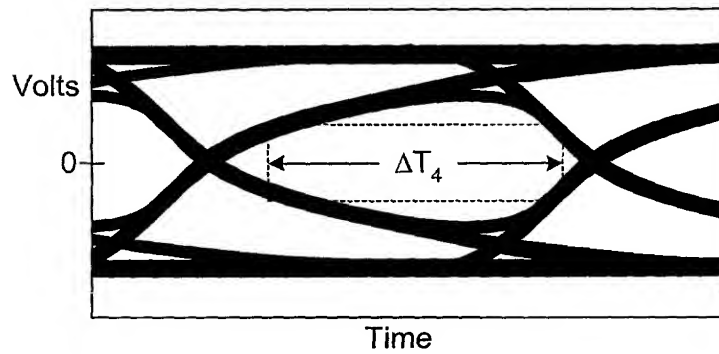


Fig. 14

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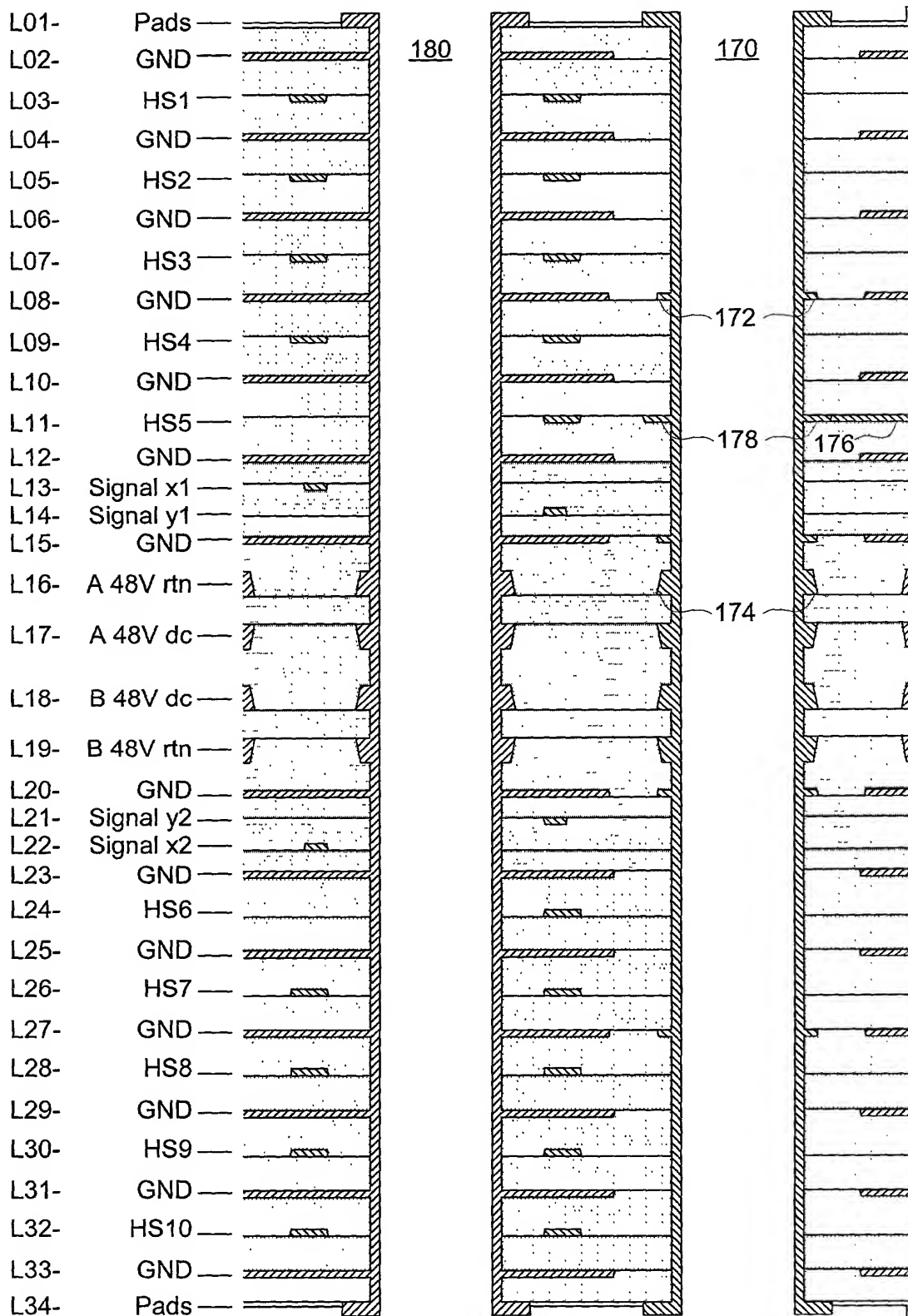
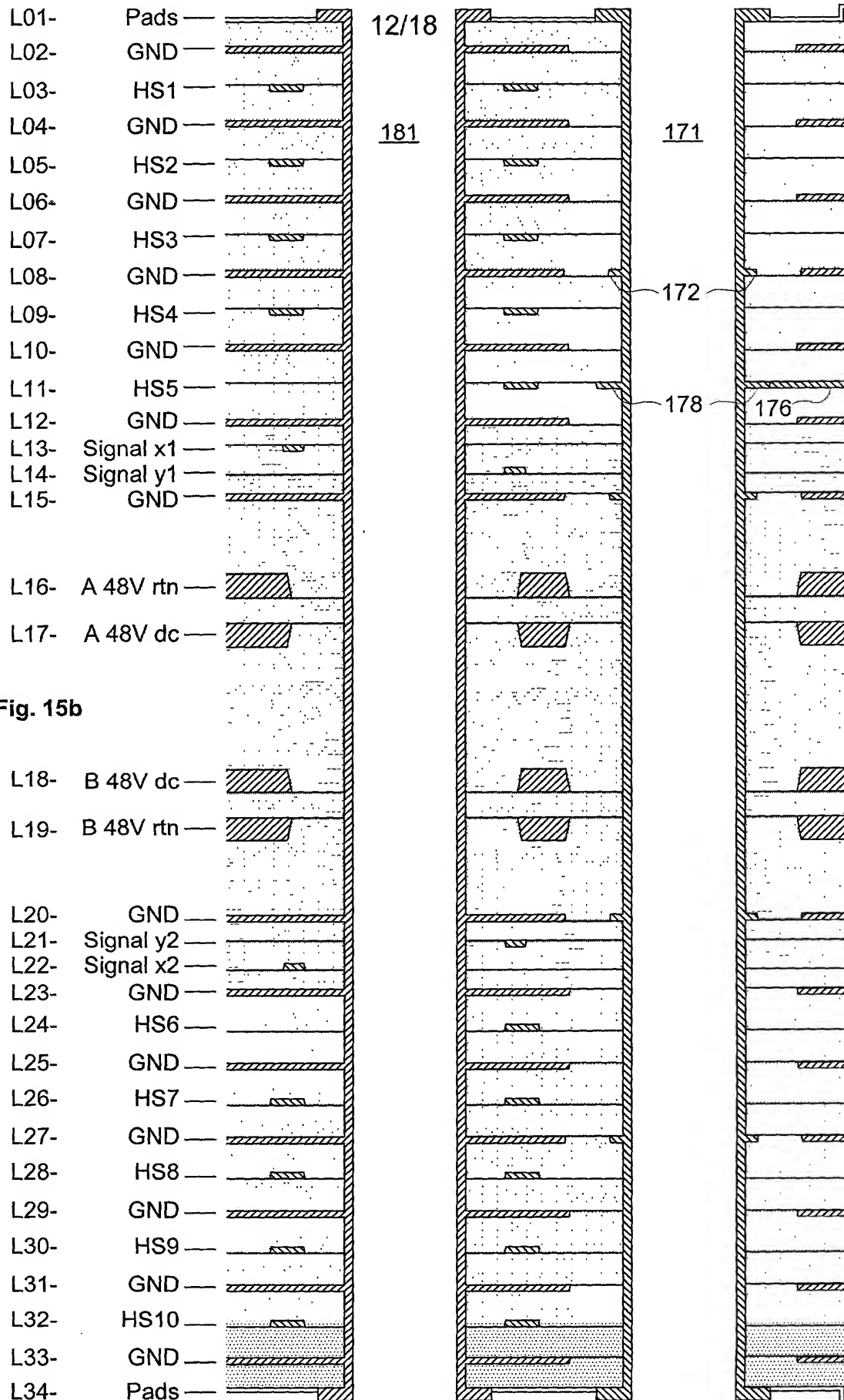


Fig. 15a



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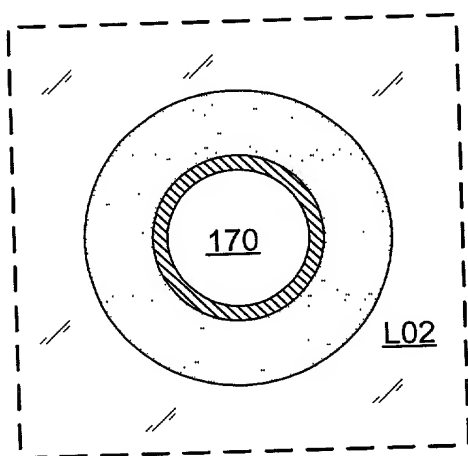


Fig. 16

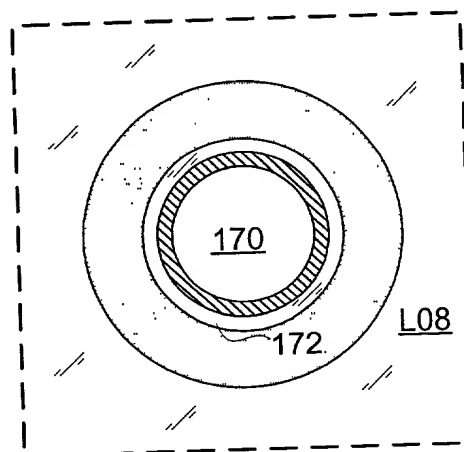


Fig. 17

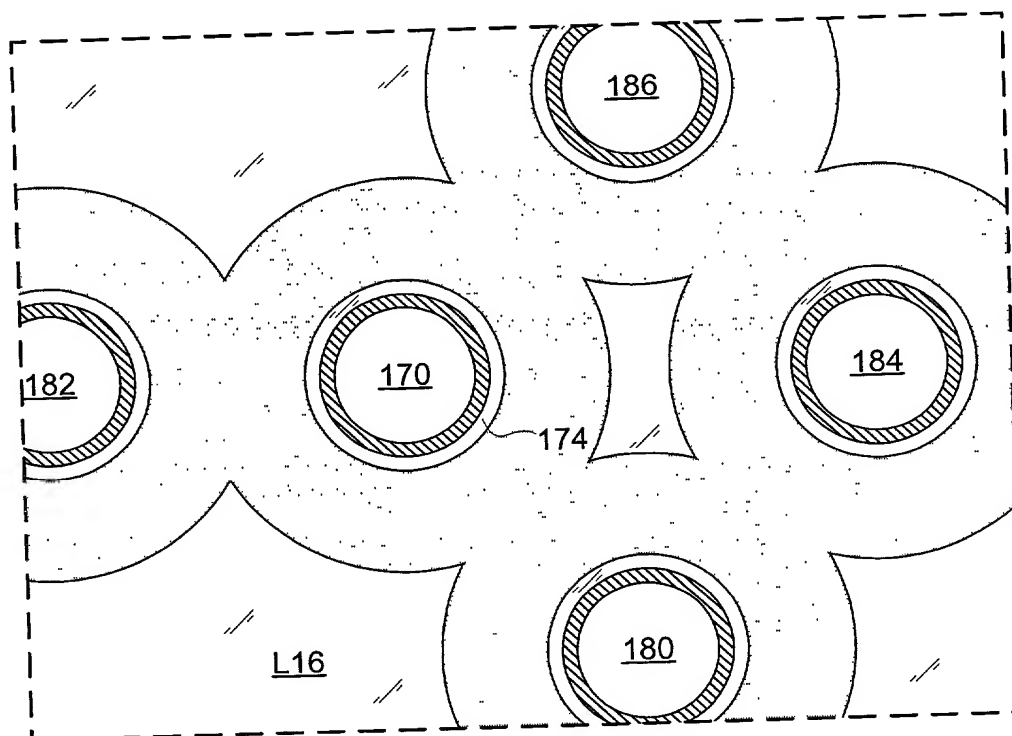


Fig. 18

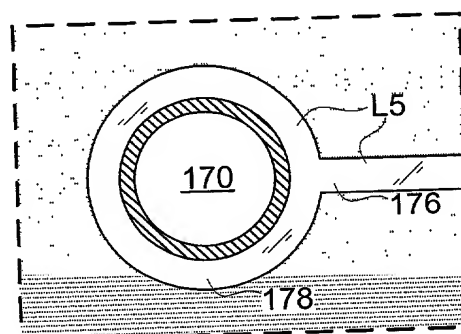
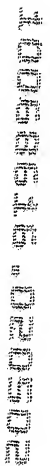


Fig. 19

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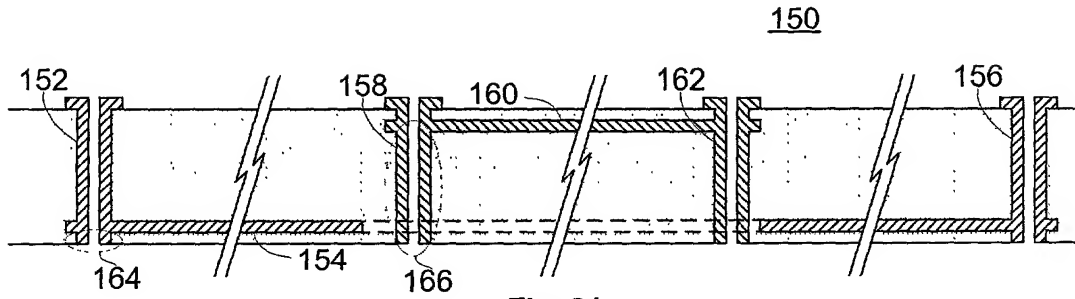


Fig. 21

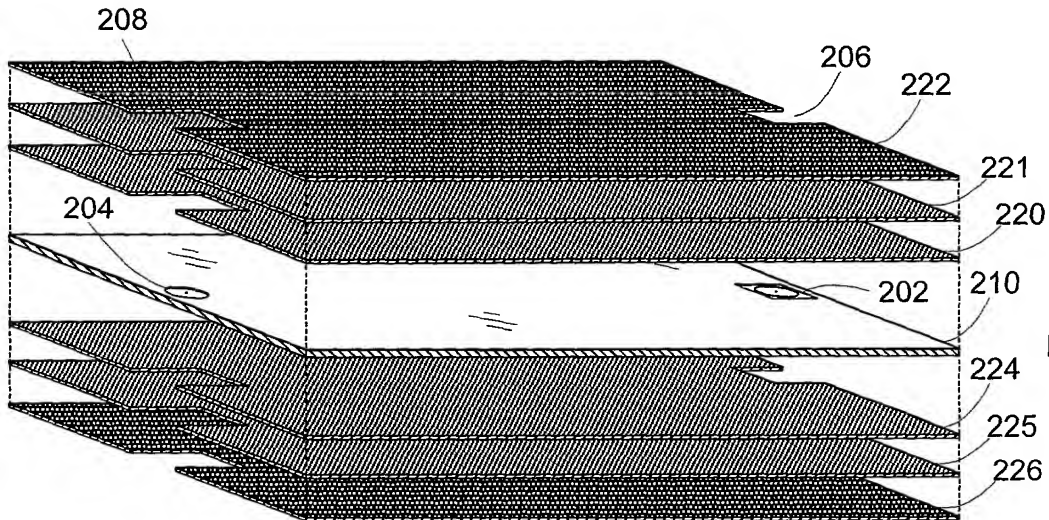


Fig. 22a

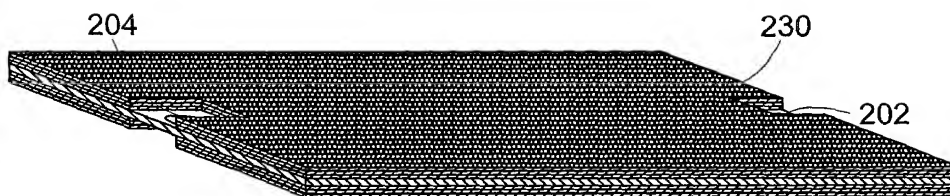


Fig. 22b

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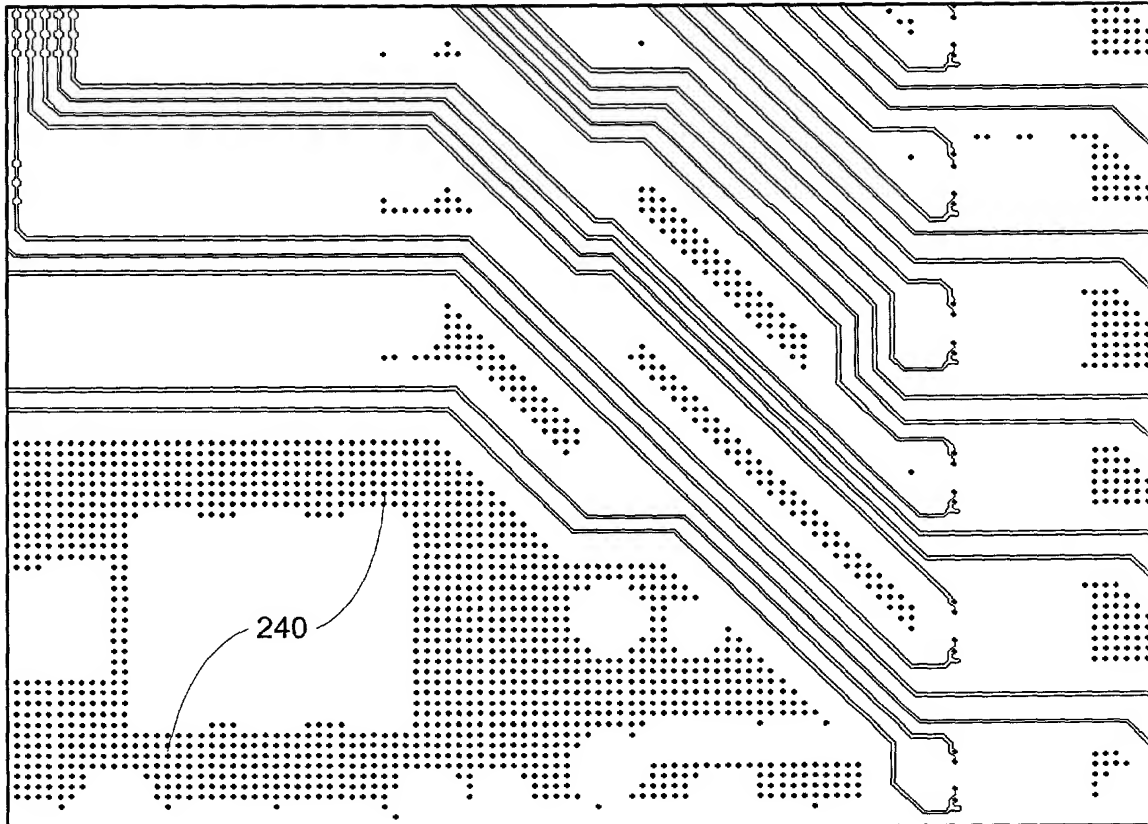


Fig. 23

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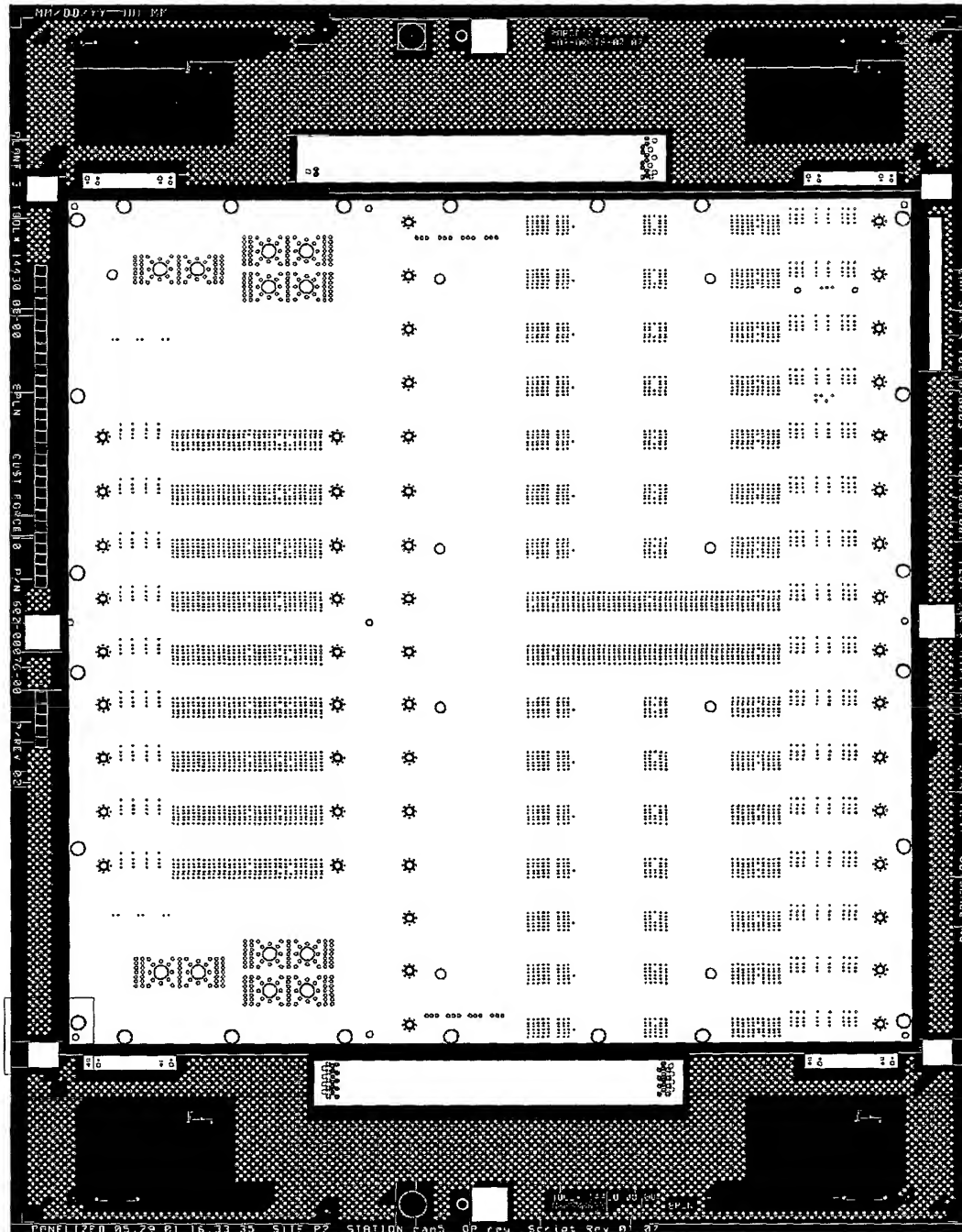


Fig. 24

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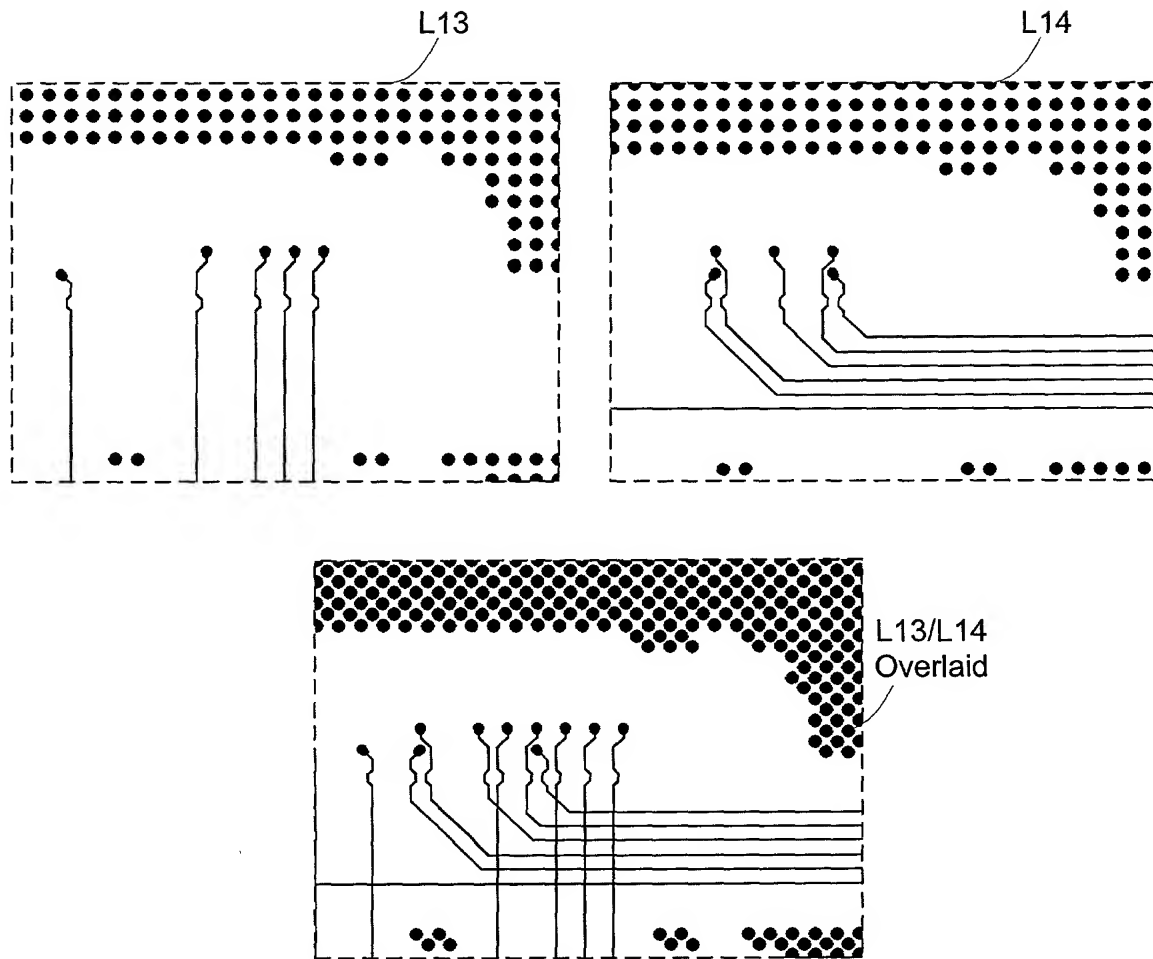


Fig. 25

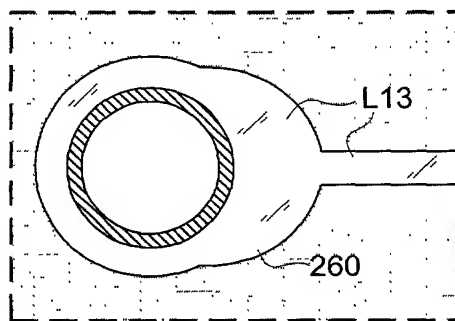


Fig. 26

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